

Positive Fixed 5V Voltage Regulator in bare die form

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Description

The 78L05AC is a 5V fixed 3-terminal voltage regulator delivering up to 100mA of output current and equipped with internal limiting + thermal shutdown features for overload immunity. Implementing this device at point-of-source removes the complexity of single point regulation methods with reduced noise. Used in replacement of a Zener diode/resistor combination, the device improves output impedance by x2 order of magnitude and delivers lower bias current with lower noise. The device can also be used with power-pass elements to make high-current voltage regulators.

Ordering Information

The following part suffixes apply:

- No suffix MIL-STD-883 /2010B Visual Inspection
- "H" MIL-PRF-883 /2010B Visual Inspection+ MIL-STD-38534 Class H LAT
- "K" MIL-PRF-883 /2010A Visual Inspection (Space)
 + MIL-STD-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

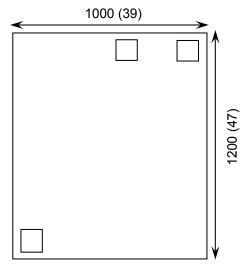
Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- With Ti/Ni/Ag Back Metal On request
- In Metal or Ceramic package On request

Features:

- ±5% V_{OUT} tolerance over entire temperature range
- 100mA Output Current
- Internal thermal overload protection
- Internal short circuit current limit
- Full Military Temperature Range
- Negative Voltage complement is 79L05AC

Die Dimensions in µm (mils)



Mechanical Specification

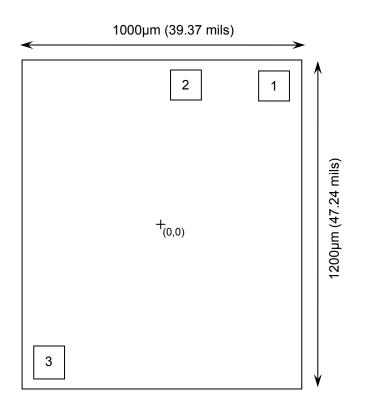
Die Size (Unsawn)	1000 x 1200 39.37 x 47.24	µm mils	
Minimum Bond Pad Size	110 x 105 4.33 x 4.13	µm mils	
Die Thickness	280 (±20) 11 (±0.8)		
Top Metal Composition	Al 1%Si 1.4μm		
Back Metal Composition	N/A – Bare Si		





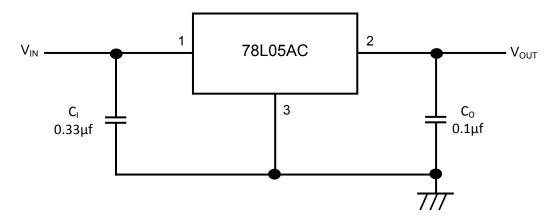
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Pad Layout and Functions



PAD	FUNCTION	COORDINATES (µm		
TAB TONGTION	X	Υ		
1	V _{IN}	312	407	
2	V _{OUT}	30	410	
3	GND	-412	-508	
CONNECT CHIP BACK TO GND				

Typical Application



 C_l is required if the regulator is located an appreciable distance from power supply filter. C_O is not required for stability; however it does improve transient response. For optimum stability and transient response locate C_l C_O as close as possible to the regulator.





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Absolute Maximum Ratings

PARAMETER	SYMBOL	VALUE	UNIT	
Input Voltage	V _{IN}	30	V	
Power Dissipation ¹	P _D	620	mW	
Operating Temperature Range	-	-55 to 125	°C	
Maximum Junction Temperature	T _J	150	°C	
Storage Temperature	T _{STG}	-65 to 150	°C	

Recommended Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	UNIT
Input Voltage	V _{IN}	7	20	V
Output Current	I _{OUT}	-	100	mA
Operating Temperature Range	T _J	-55	125	°C

$DC \ Electrical \ Characteristics, \ V_i = 10V, \ I_{OUT} = 40 mA, C_i = 0.33 \mu F, \ C_O = 0.1 \mu f, \ 0^{\circ}C < T_J < +125^{\circ}C (unless \ noted \ otherwise)$

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Output Voltage	V _{OUT}	$T_J = 25^{\circ}\text{C}, I_O = 40\text{mA}$	4.80	5.00	5.20	V
		$1\text{mA} \le I_{\text{OUT}} \le 40\text{mA}, 7\text{V} \le V_{\text{IN}} \le 20\text{V}$	4.75	5.00	5.25	
		$1\text{mA} \le I_{\text{OUT}} \le 70\text{mA}, V_{\text{IN}} = 10\text{V}$	4.75	5.00	5.25	
Line Regulation Δ	ΔV_{OUT}	$7V \le V_{IN} \le 20V$, $T_J = 25$ °C, $I_O = 40$ mA	-	32	150	
	A V OUT	$8V \le V_{IN} \le 20V$, $T_J = 25$ °C, $I_O = 40$ mA	-	26	100	mV
Load Regulation	ΔV _{OUT}	$1\text{mA} \le I_{\text{OUT}} \le 100\text{mA}, T_{\text{J}} = 25^{\circ}\text{C}$	-	15	60	IIIV
		1mA ≤ I _{OUT} ≤ 40mA, T _J = 25°C	-	8	30	
Input Bias Current	I _B	T _J = 25°C	-	3.8	6.0	mA
		T _J = 125°C	-	-	5.5	111/4
Input Bias Current Change ΔI _B	8V ≤ V _{IN} ≤ 20V	-	-	1.5	mA	
	ΔIB	1mA ≤ I _{OUT} ≤ 40mA	-	-	0.1	ША
Output Noise Voltage	e _N	10Hz ≤ f ≤ 100KHz, T _A = 25°C	-	42	-	μV_{RMS}
Ripple Rejection	RR	f = 120Hz, 8V ≤ V _{IN} ≤ 18V, T _J = 25°C	41	49	-	dB
Dropout Voltage	V_D	V _{IN} -V _{OUT}	-	1.7	-	V

^{1.} Value measured in TO-92 package applicable only for DC power dissipation permitted by absolute maximum ratings. Results in die form are dependent on die attach and assembly method.





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